

To our customers,

Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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Not recommended
for new design

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HSK122

Silicon Epitaxial Planar Diode for High Voltage Switching

RENESAS

ADE-208-172D (Z)

Rev.4
Dec. 2000

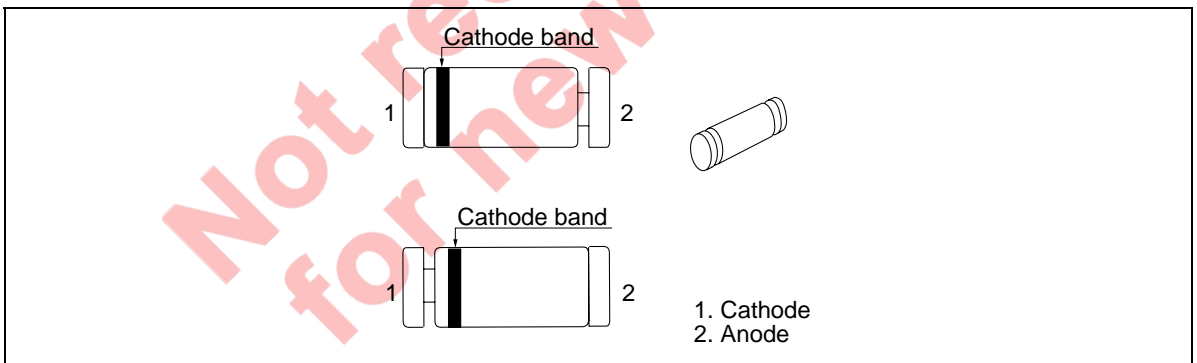
Features

- High reverse voltage. ($V_R = 400\text{ V}$)
- LLD package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Cathode band	Package Code
HSK122	Orange	LLD

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	410	V
Reverse voltage	V_R	400	V
Peak forward current	I_{FM}	625	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*1}	1	A
Average forward current	I_O	150	mA
Junction temperature	Tj	175	°C
Storage temperature	Tstg	-65 to +175	°C

Note: Within 1s forward surge current.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	1.2	V	$I_F = 100 \text{ mA}$
Reverse current	I_R	—	—	1.0	μA	$V_R = 400 \text{ V}$
Capacitance	C	—	—	10	pF	$V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$
Reverse recovery time	t_{rr}	—	—	10	μs	$I_F = 30 \text{ mA}$, $V_R = 10 \text{ V}$, $R_L = 2 \text{ k}\Omega$

Main Characteristic

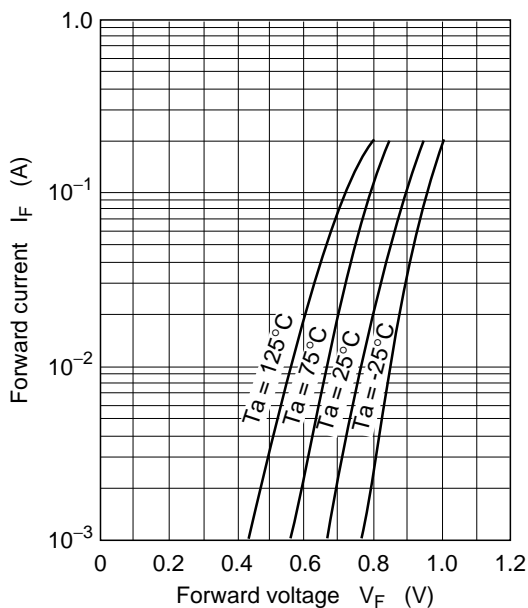


Fig.1 Forward current Vs. Forward voltage

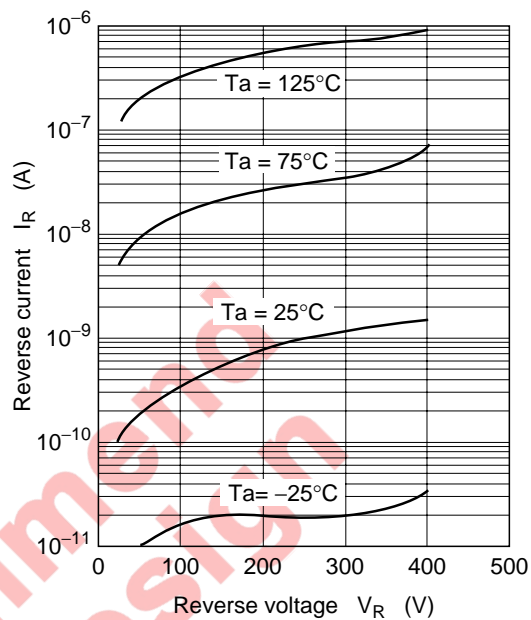


Fig.2 Reverse current Vs. Reverse voltage

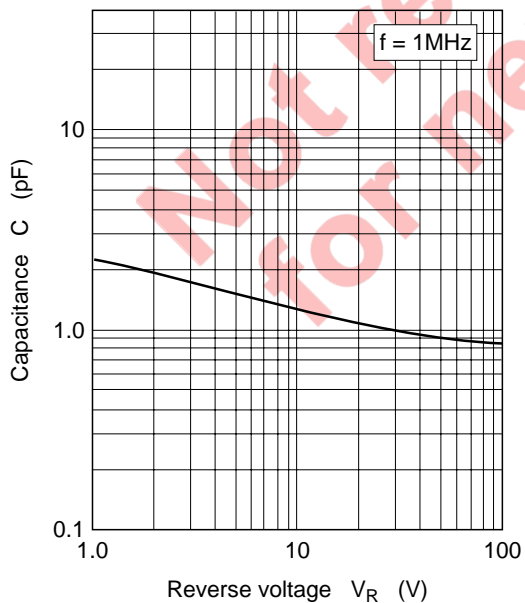
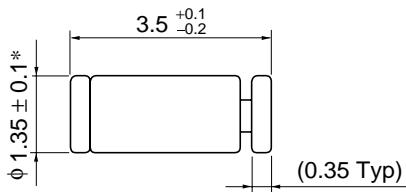


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



* HSK122: $\phi 1.4 \pm 0.1$ type

Hitachi Code	LLD
JEDEC	—
EIAJ	—
Mass (reference value)	0.027 g

Not recommended
for new designs

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits
 Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
 Tel: (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica	: http://semiconductor.hitachi.com/
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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1> (408) 433-0223	Hitachi Europe Ltd. Electronic Components Group Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 585200
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Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00
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Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00 Singapore 049318 Tel: <65>-538-6533/538-8577 Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg
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Hitachi Asia Ltd. (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road Hung-Kuo Building Taipei (105), Taiwan Tel: <886>-(2)-2718-3666 Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon Hong Kong Tel: <852>-(2)-735-9218 Fax: <852>-(2)-730-0281 URL: http://semiconductor.hitachi.com.hk
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